

RCJ120N25

Nch 250V 12A Power MOSFET

V_{DSS}	250V
R _{DS(on)} (Max.)	235m Ω
I _D	12A
P_D	107W

● Features

- 1) Low on-resistance.
- 2) Fast switching speed.
- 3) Drive circuits can be simple.
- 4) Parallel use is easy.
- 5) Pb-free lead plating; RoHS compliant
- 6) 100% Avalanche tested

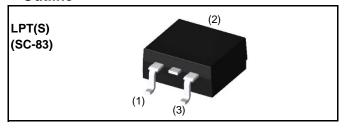
Application

Switching Power Supply

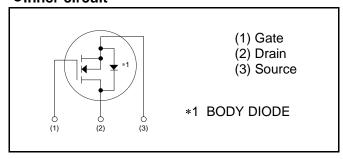
Automotive Motor Drive

Automotive Solenoid Drive

Outline



•Inner circuit



Packaging specifications

	Packaging	Taping
	Reel size (mm)	330
Type	Tape width (mm)	24
Туре	Quantity (pcs)	1,000
	Taping code	TL
	Marking	RCJ120N25

● Absolute maximum ratings(T_a = 25°C)

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V_{DSS}	250	V	
Continuous drain current	T _c = 25°C	I _D *1	±12	А
Continuous drain current	T _c = 100°C	I _D *1	±6.5	А
Pulsed drain current		I _{D,pulse} *2	±48	А
Gate - Source voltage		V_{GSS}	±30	V
Avalanche energy, single pulse		E _{AS} *3	10.5	mJ
Avalanche current		I _{AR} *3	6.0	А
$T_c = 25^{\circ}C$		P_{D}	107	W
Power dissipation $T_a = 25^{\circ}C^{^{*4}}$		P_{D}	1.56	W
Junction temperature		T _j	150	°C
Range of storage temperature		T _{stg}	−55 to +150	°C

●Thermal resistance

Parameter	Symbol	Values			Unit
- Farameter	Symbol	Min.	Тур.	Max.	Offic
Thermal resistance, junction - case	R_{thJC}	-	-	1.16	°C/W
Thermal resistance, junction - ambient *4	R_{thJA}	-	-	80	°C/W
Soldering temperature, wavesoldering for 10s	T_{sold}	-	-	265	°C

•Electrical characteristics($T_a = 25$ °C)

Parameter	Symbol	Conditions			Values		
r ai ai iletei	Syllibol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V$, $I_D = 1mA$	250	-	-	V	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 250V, V_{GS} = 0V$ $T_{j} = 25^{\circ}C$	-	1	10	μА	
Gate - Source leakage current	I_{GSS}	$V_{GS} = \pm 30V, V_{DS} = 0V$	ı	ı	±100	nA	
Gate threshold voltage	V _{GS (th)}	$V_{DS} = 10V$, $I_D = 1mA$	3.0	-	5.0	V	
		$V_{GS} = 10V, I_D = 6.0A$	-	180	235		
Static drain - source on - state resistance	R _{DS(on)} *5	$V_{GS} = 10V, I_D = 6.0A$ $T_j = 125^{\circ}C$	-	340	480	mΩ	
Forward transfer admittance	g _{fs}	$V_{DS} = 10V, I_{D} = 6.0A$	3.25	6.50	-	S	

●Electrical characteristics(T_a = 25°C)

Parameter	Symbol	Conditions		Unit		
r ai ai ii e lei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Input capacitance	C _{iss}	$V_{GS} = 0V$	-	1800	-	
Output capacitance	C _{oss}	V _{DS} = 25V	-	100	-	pF
Reverse transfer capacitance	C_{rss}	f = 1MHz	-	60	-	
Turn - on delay time	t _{d(on)} *5	$V_{DD} \simeq 125V, V_{GS} = 10V$	-	33	-	
Rise time	t _r *5	$I_{D} = 6.0A$	-	65	-	nc
Turn - off delay time	t _{d(off)} *5	$R_L = 12\Omega$	-	45	-	ns
Fall time	t _f *5	$R_G = 10\Omega$	-	20	-	

● Gate Charge characteristics (T_a = 25°C)

Parameter	Cymbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*5}	V _{DD} ≃ 125V	-	35	-	
Gate - Source charge	Q _{gs} *5	I _D = 12A	-	15	-	nC
Gate - Drain charge	Q _{gd} *5	V _{GS} = 10V	-	12	-	
Gate plateau voltage	V _(plateau)	$V_{DD} \simeq 125V, I_D = 12A$	-	7.6	-	V

●Body diode electrical characteristics (Source-Drain)(T_a = 25°C)

Parameter	Symbol	Conditions	Values			Unit
r ai ai i letei	Syllibol	Conditions	Min.	Тур.	Max.	Offic
Continuous source current	l _S *1	T _c = 25°C	ı	-	12	Α
Pulsed source current	I _{SM} *2	1 _c = 25 C	ı	1	48	Α
Forward voltage	V _{SD} *5	$V_{GS} = 0V, I_{S} = 12A$	-	-	1.5	V
Reverse recovery time	t _{rr} *5	I _S = 6.0A	-	105	-	ns
Reverse recovery charge	Q _{rr} *5	di/dt = 100A/μs	-	410	-	nC

^{*1} Limited only by maximum temperature allowed.

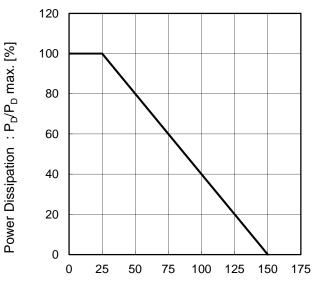
*5 Pulsed

^{*2} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*3} L $^{\simeq}$ 500 μ H, V_{DD} = 50V, Rg = 25 Ω , starting T $_{j}$ = 25°C

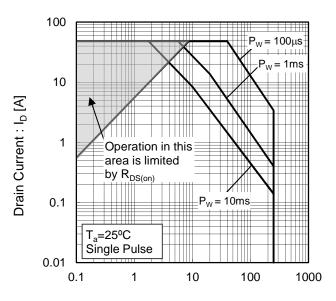
^{*4} Mounted on a epoxy PCB FR4 (25mm × 27mm × 0.8mm)

Fig.1 Power Dissipation Derating Curve



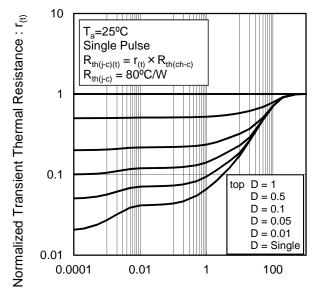
Junction Temperature : T_i [°C]

Fig.2 Maximum Safe Operating Area



Drain - Source Voltage : V_{DS} [V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width



Pulse Width : $P_W[s]$

Fig.4 Avalanche Current vs Inductive Load

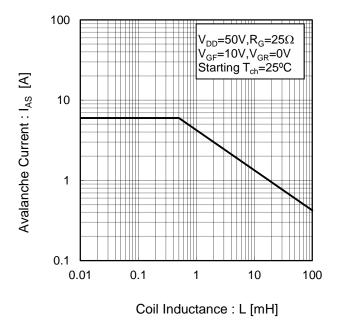
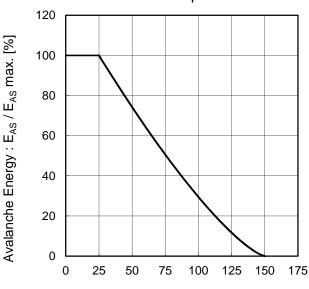
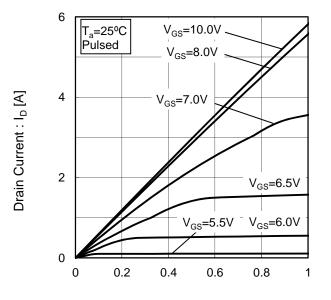


Fig.5 Avalanche Energy Derating Curve vs Junction Temperature



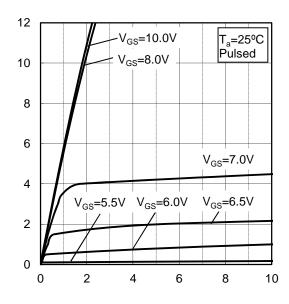
Junction Temperature : T_i [°C]

Fig.6 Typical Output Characteristics(I)



Drain - Source Voltage : V_{DS} [V]

Fig.7 Typical Output Characteristics(II)



Drain - Source Voltage : V_{DS} [V]

Drain Current : I_D [A]

Fig.8 Breakdown Voltage vs. Junction Temperature 340 Normarize Drain - Source Breakdown Voltage $V_{GS} = 0V$ $I_D = 1 \text{mA}$ 320 300 280 260 240 220 -50 0 50 100 150 Junction Temperature : T_i [°C]

Fig.9 Typical Transfer Characteristics 100 $V_{DS} = 10V$ 10

Drain Current: I_D [A] 0.1 T_a= 75°C $T_a = 25^{\circ}C$ $T_a = -25^{\circ}C$ 0.01 0.001 0 3 4 5 6

Gate - Source Voltage : V_{GS} [V]

Fig.10 Gate Threshold Voltage vs. Junction Temperature

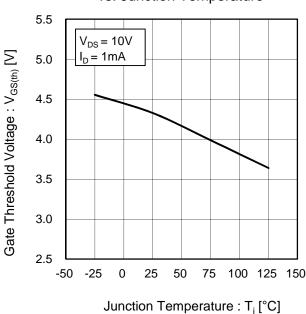
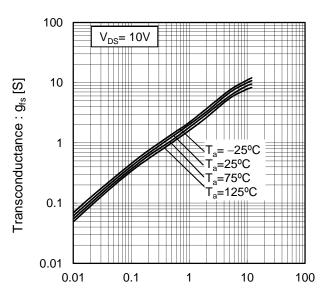


Fig.11 Transconductance vs. Drain Current



Drain Current : I_D [A]

Fig.12 Static Drain - Source On - State Fig.13 Static Drain - Source On - State Resistance vs. Gate Source Voltage Resistance vs. Drain Current(I) 500 1000 Static Drain - Source On-State Resistance T_a=25°C Static Drain - Source On-State Resistance T_a=25°C 450 400 $V_{GS} = 10V$ 350 300 $:R_{DS(on)}\left[m\Omega \right]$ $I_D = 12A$ $:R_{\text{DS(on)}}\left[\text{m}\Omega \right]$ 250 100 $I_{D} = 6.0A$ 200 150 100 50 10 0 0 6 8 10 12 14 16 18 20 0.01 0.1 1 10 100 Gate - Source Voltage : V_{GS} [V] Drain Current : I_D [A]

Fig.14 Static Drain - Source On - State Resistance vs. Junction Temperature

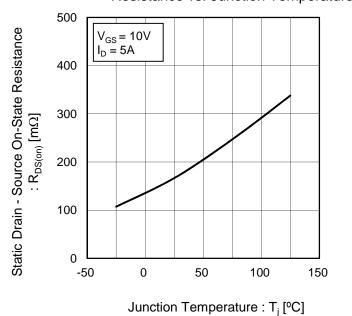


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current(II)

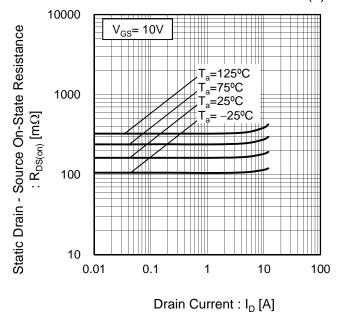
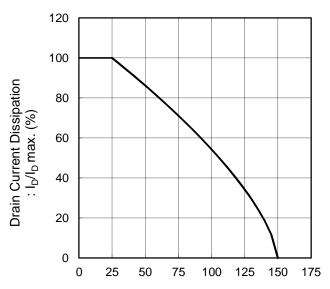
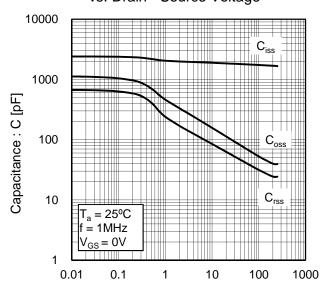


Fig.16 Drain Current Derating Curve



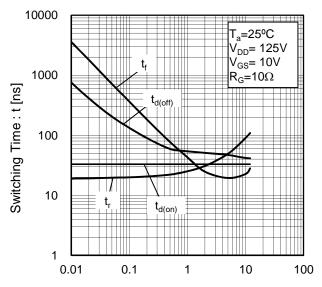
Junction Temperature : T_i [°C]

Fig.17 Typical Capacitance vs. Drain - Source Voltage



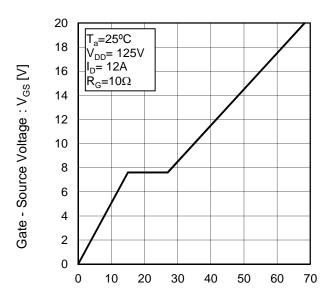
Drain - Source Voltage : V_{DS} [V]

Fig.18 Switching Characteristics

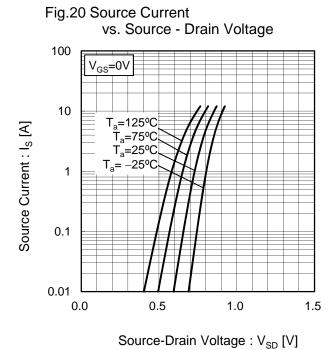


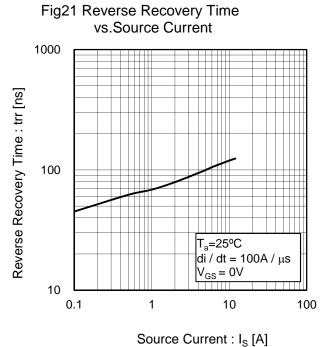
Drain Current : I_D [A]

Fig.19 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]





●Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

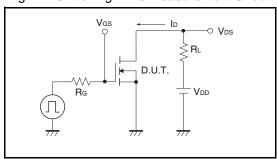


Fig.2-1 Gate Charge Measurement Circuit

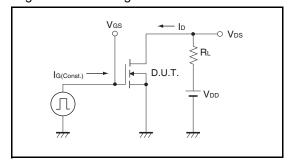


Fig.3-1 Avalanche Measurement Circuit

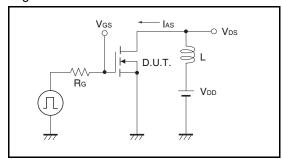


Fig.1-2 Switching Waveforms

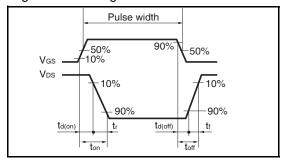


Fig.2-2 Gate Charge Waveform

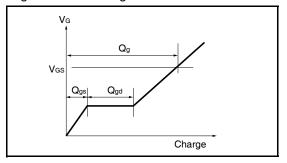
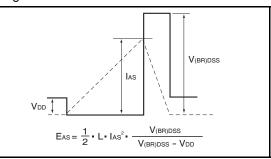
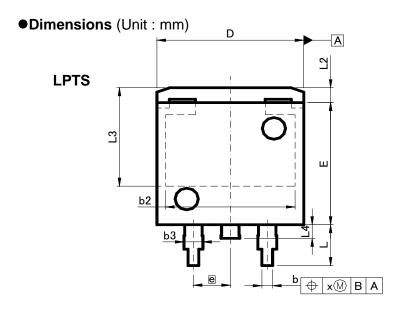
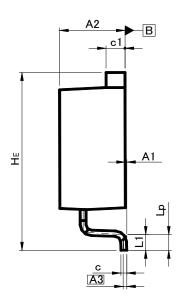
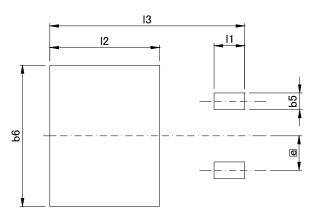


Fig.3-2 Avalanche Waveform









Patterm of terminal position areas

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
A1	0.00	0.30	0	0.012
A2	4.30	4.70	0.169	0.185
A3	0.:	25	0.	01
b	0.68	0.98	0.027	0.039
b2	8.	90	0.	35
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.	54	0.	10
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.13
L1	0.90	1.50	0.035	0.059
L2	1.	10	0.0)43
L3	7.	25	0.2	85
L4	1.	00	0.0	39
Lp	0.90	1.50	0.035	0.059
Х	_	0.25	_	0.01

DIM	MILIMETERS INCHES			HES
DIIVI	MIN	MAX	MIN	MAX
b5	ı	1.23	ı	0.049
b6	İ	10.40	İ	0.409
11	-	2.10	-	0.083
12	=	7.55	-	0.297
13	_	13.40	_	0.528

Dimension in mm/inches

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CLASSⅢ	О 400 Ш	CLASS II b	CL ACCIII
CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
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- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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